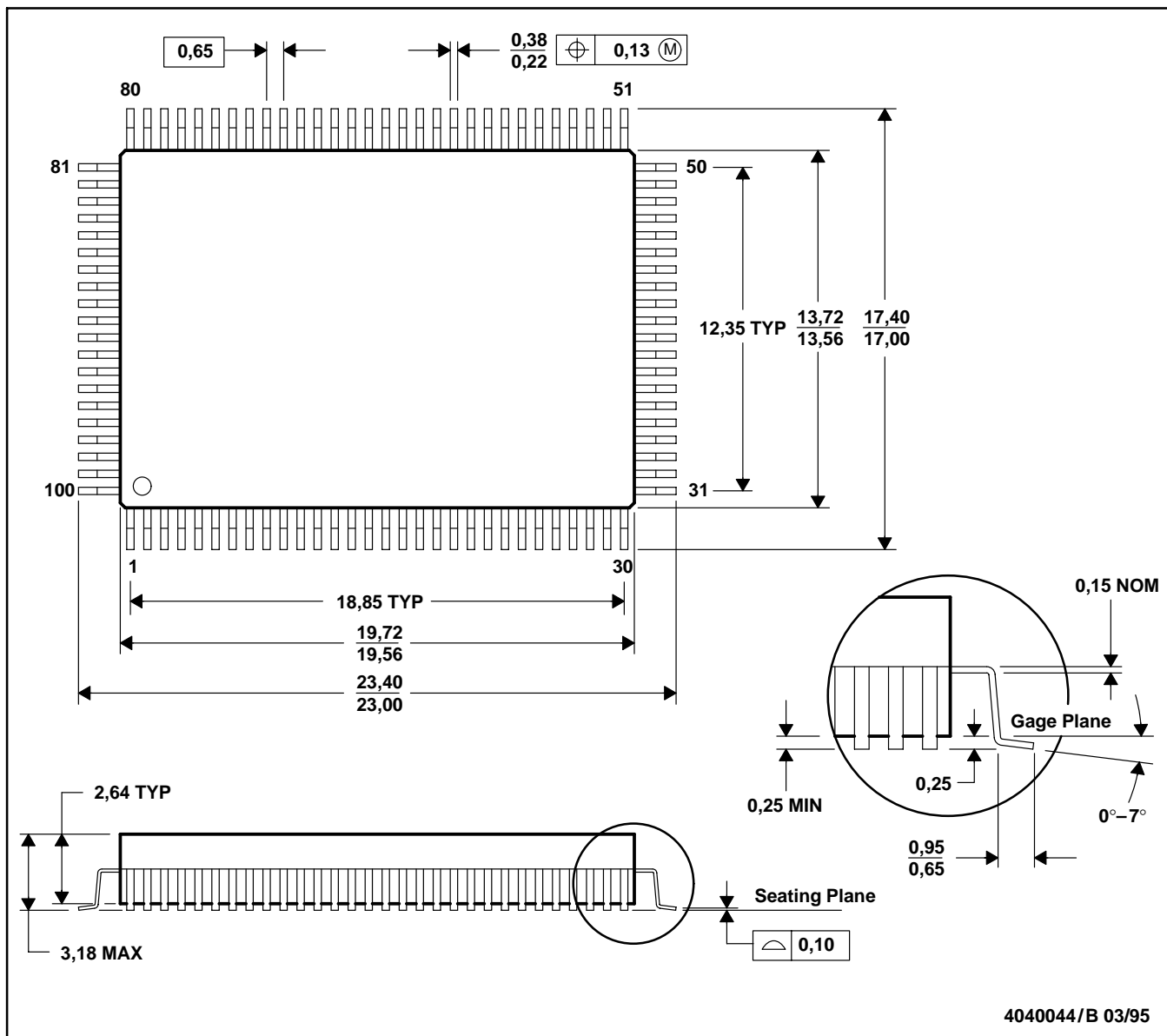


## MBM (R-MQFP-G100)

## METAL QUAD (MQUAD®) FLATPACK (DIE-DOWN)



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. MQUAD is a registered trademark of Olin Corporation.  
 D. This quad flatpack consists of a circuit mounted on a leadframe and encased within an anodized aluminum shell. The package is intended for parts requiring either a lower stress environment or higher thermal dissipation capabilities than can be supplied by plastic.

CAUTION: Ultrasonic cleaning of this package or boards with this package is not permitted.

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